



# STP5NB40 STP5NB40FP

N-CHANNEL 400V - 1.47Ω - 4.7A TO-220/TO-220FP  
PowerMesh™ MOSFET

TYPE	V <sub>DSS</sub>	R <sub>D(on)</sub>	I <sub>D</sub>
STP5NB40	400 V	< 1.8 Ω	4.7 A
STP5NB40FP	400 V	< 1.8 Ω	4.7 A

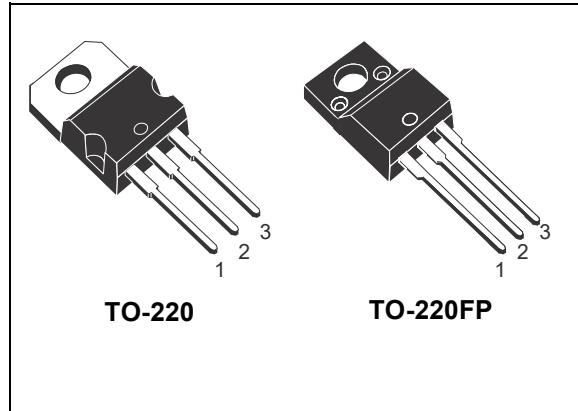
- TYPICAL R<sub>D(on)</sub> = 1.47 Ω
- EXTREMELY HIGH dv/dt CAPABILITY
- 100% AVALANCHE TESTED
- VERY LOW INTRINSIC CAPACITANCES
- GATE CHARGE MINIMIZED

## DESCRIPTION

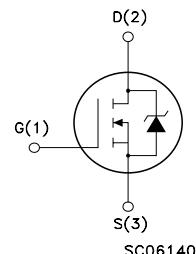
Using the latest high voltage MESH OVERLAY™ process, STMicroelectronics has designed an advanced family of power MOSFETs with outstanding performances. The new patent pending strip layout coupled with the Company's proprietary edge termination structure, gives the lowest R<sub>D(on)</sub> per area, exceptional avalanche and dv/dt capabilities and unrivalled gate charge and switching characteristics.

## APPLICATIONS

- HIGH CURRENT, HIGH SPEED SWITCHING
- SWITH MODE POWER SUPPLIES (SMPS)
- DC-AC CONVERTERS FOR WELDING EQUIPMENT



## INTERNAL SCHEMATIC DIAGRAM



## ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value		Unit
		STP5NB40	STP5NB40FP	
V <sub>DS</sub>	Drain-source Voltage (V <sub>GS</sub> = 0)	400	400	V
V <sub>DGR</sub>	Drain-gate Voltage (R <sub>GS</sub> = 20 kΩ)	400	400	V
V <sub>GS</sub>	Gate- source Voltage	±30	±30	V
I <sub>D</sub>	Drain Current (continuos) at T <sub>C</sub> = 25°C	4.7	4.7 (*)	A
I <sub>D</sub>	Drain Current (continuos) at T <sub>C</sub> = 100°C	3	3 (*)	A
I <sub>DM</sub> (•)	Drain Current (pulsed)	19	19 (*)	A
P <sub>TOT</sub>	Total Dissipation at T <sub>C</sub> = 25°C	80	30	W
	Derating Factor	0.64	0.24	W/°C
dv/dt (1)	Peak Diode Recovery voltage slope	4	4	V/ns
V <sub>ISO</sub>	Insulation Withstand Voltage (DC)	-	2500	V
T <sub>stg</sub>	Storage Temperature	-65 to 150		°C
T <sub>j</sub>	Max. Operating Junction Temperature	150		°C

(•)Pulse width limited by safe operating area

(\*)Limited only by maximum temperature allowed

(1)I<sub>SD</sub> ≤ 4.7A, dI/dt ≤ 200A/μs, V<sub>DD</sub> ≤ V<sub>(BR)DSS</sub>, T<sub>j</sub> ≤ T<sub>JMAX</sub>.

## STP5NB40/FP

### THERMAL DATA

		TO-220	TO-220FP	
Rthj-case	Thermal Resistance Junction-case Max	1.56	4.1	°C/W
Rthj-amb T <sub>I</sub>	Thermal Resistance Junction-ambient Max Maximum Lead Temperature For Soldering Purpose	62.5 300		°C/W °C

### AVALANCHE CHARACTERISTICS

Symbol	Parameter	Max Value	Unit
I <sub>AR</sub>	Avalanche Current, Repetitive or Not-Repetitive (pulse width limited by T <sub>j</sub> max)	4.7	A
E <sub>AS</sub>	Single Pulse Avalanche Energy (starting T <sub>j</sub> = 25 °C, I <sub>D</sub> = I <sub>AR</sub> , V <sub>DD</sub> = 50 V)	200	mJ

### ELECTRICAL CHARACTERISTICS (TCASE = 25 °C UNLESS OTHERWISE SPECIFIED) OFF

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V <sub>(BR)DSS</sub>	Drain-source Breakdown Voltage	I <sub>D</sub> = 250 μA, V <sub>GS</sub> = 0	400			V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current (V <sub>GS</sub> = 0)	V <sub>DS</sub> = Max Rating V <sub>DS</sub> = Max Rating, T <sub>C</sub> = 125 °C			1 50	μA μA
I <sub>GSS</sub>	Gate-body Leakage Current (V <sub>DS</sub> = 0)	V <sub>GS</sub> = ±30V			±100	nA

### ON (1)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA	3	4	5	V
R <sub>DS(on)</sub>	Static Drain-source On Resistance	V <sub>GS</sub> = 10V, I <sub>D</sub> = 2.3 A		1.47	1.8	Ω

### DYNAMIC

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
g <sub>fs</sub> (1)	Forward Transconductance	V <sub>DS</sub> > I <sub>D(on)</sub> × R <sub>DS(on)max</sub> , I <sub>D</sub> = 2.3 A		2.4		S
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = 25V, f = 1 MHz, V <sub>GS</sub> = 0		405		pF
C <sub>oss</sub>	Output Capacitance			72		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			9		pF

**ELECTRICAL CHARACTERISTICS (CONTINUED)****SWITCHING ON**

<b>Symbol</b>	<b>Parameter</b>	<b>Test Conditions</b>	<b>Min.</b>	<b>Typ.</b>	<b>Max.</b>	<b>Unit</b>
$t_{d(on)}$	Turn-on Delay Time	$V_{DD} = 200\text{ V}$ , $I_D = 2.5\text{ A}$		11		ns
$t_r$	Rise Time	$R_G = 4.7\Omega$ , $V_{GS} = 10\text{ V}$ (see test circuit, Figure 3)		8		ns
$Q_g$	Total Gate Charge	$V_{DD} = 320\text{V}$ , $I_D = 5\text{ A}$ ,		14.5		nC
$Q_{gs}$	Gate-Source Charge	$V_{GS} = 10\text{V}$		7		nC
$Q_{gd}$	Gate-Drain Charge			5.1		nC

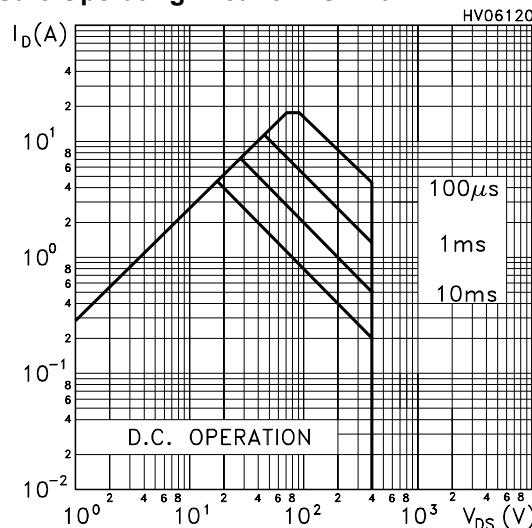
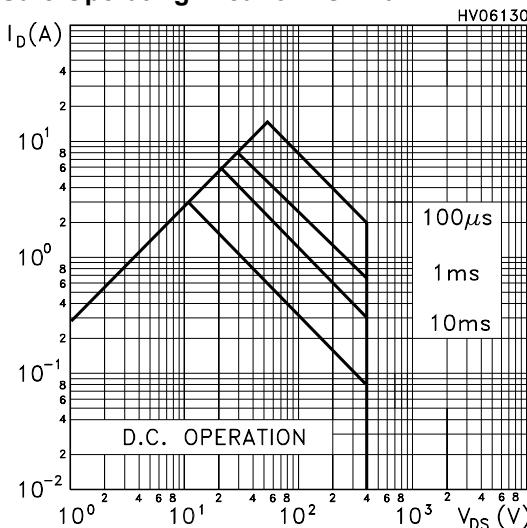
**SWITCHING OFF**

<b>Symbol</b>	<b>Parameter</b>	<b>Test Conditions</b>	<b>Min.</b>	<b>Typ.</b>	<b>Max.</b>	<b>Unit</b>
$t_{r(V_{off})}$	Off-voltage Rise Time	$V_{DD} = 320\text{V}$ , $I_D = 5\text{ A}$ ,		9		ns
$t_f$	Fall Time	$R_G = 4.7\Omega$ , $V_{GS} = 10\text{V}$ (see test circuit, Figure 5)		6		ns
$t_c$	Cross-over Time			14		ns

**SOURCE DRAIN DIODE**

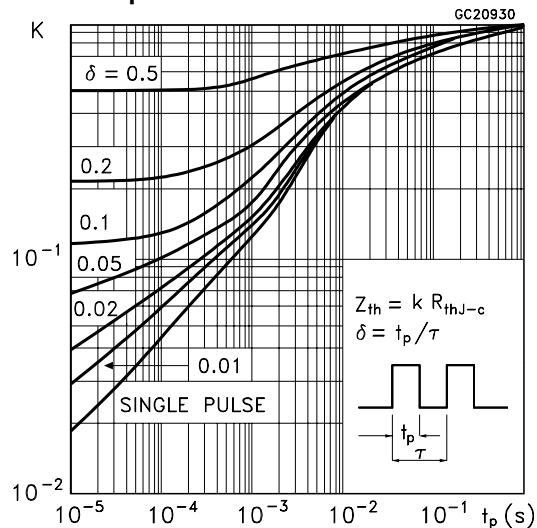
<b>Symbol</b>	<b>Parameter</b>	<b>Test Conditions</b>	<b>Min.</b>	<b>Typ.</b>	<b>Max.</b>	<b>Unit</b>
$I_{SD}$	Source-drain Current				4.7	A
$I_{SDM}(1)$	Source-drain Current (pulsed)				19	A
$V_{SD}(2)$	Forward On Voltage	$I_{SD} = 4.7\text{ A}$ , $V_{GS} = 0$			1.6	V
$t_{rr}$	Reverse Recovery Time	$I_{SD} = 5\text{ A}$ , $dI/dt = 100\text{A}/\mu\text{s}$ ,		300		ns
$Q_{rr}$	Reverse Recovery Charge	$V_{DD} = 100\text{V}$ , $T_j = 150^\circ\text{C}$ (see test circuit, Figure 5)		1.6		$\mu\text{C}$
$I_{RRM}$	Reverse Recovery Current			10.5		A

Note: 1. Pulsed: Pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5 %.  
2. Pulse width limited by safe operating area.

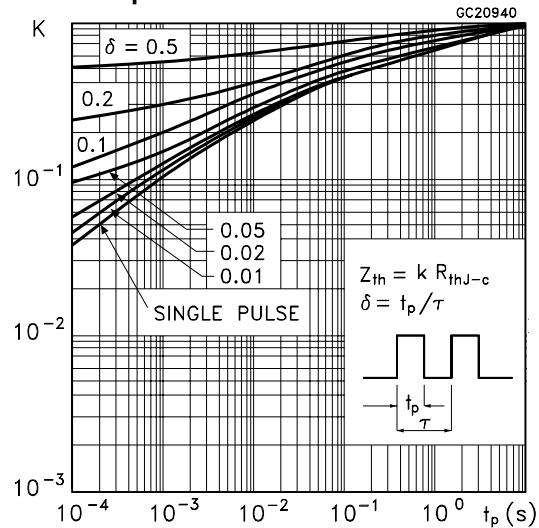
**Safe Operating Area for TO-220****Safe Operating Area for TO-220FP**

## STP5NB40/FP

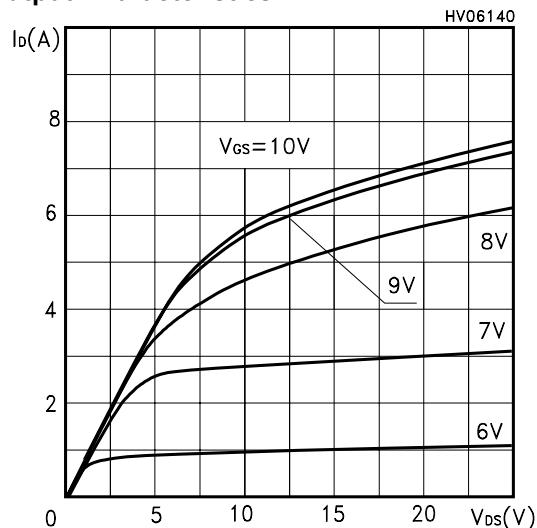
### Thermal Impedance for TO-220



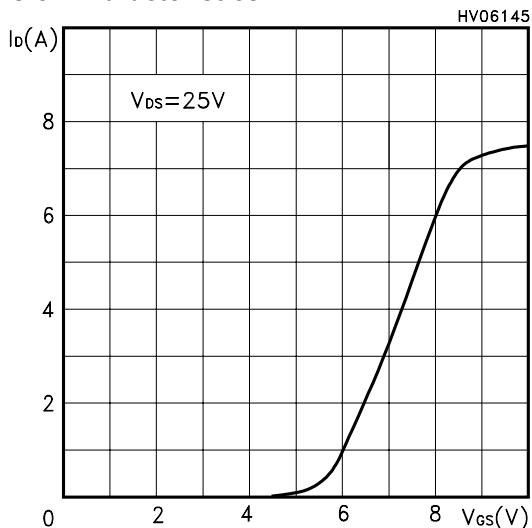
### Thermal Impedance for TO-220FP



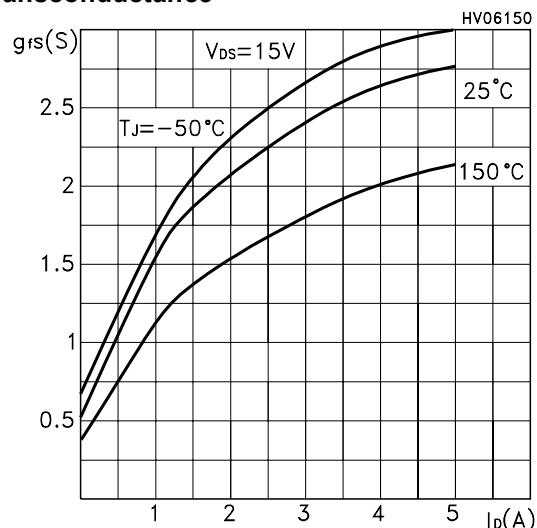
### Output Characteristics



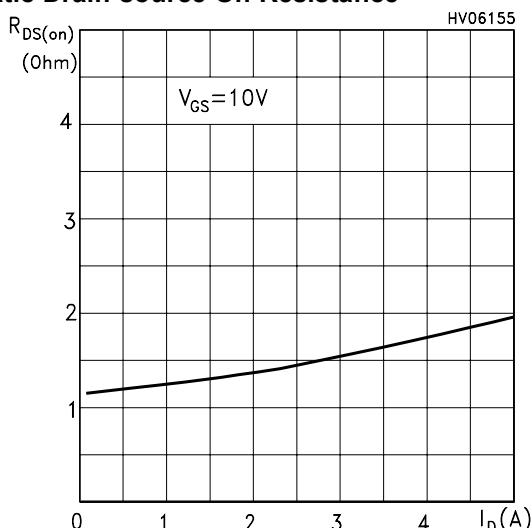
### Transfer Characteristics



### Transconductance

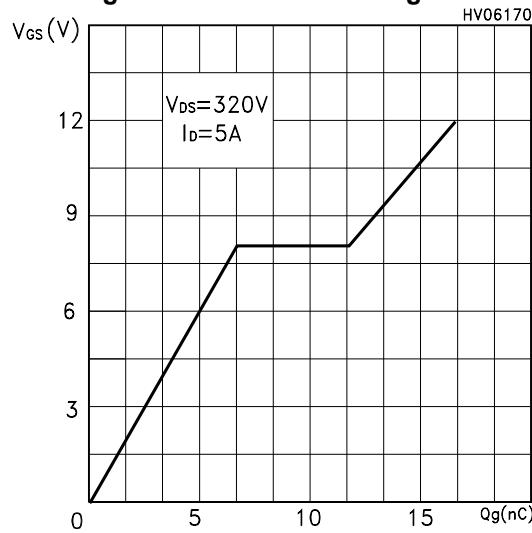


### Static Drain-source On Resistance

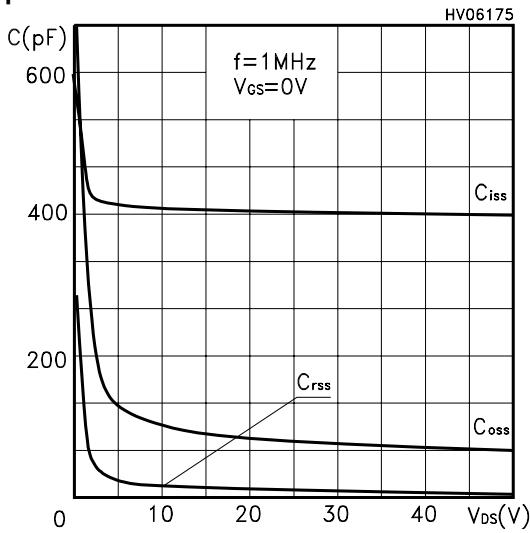


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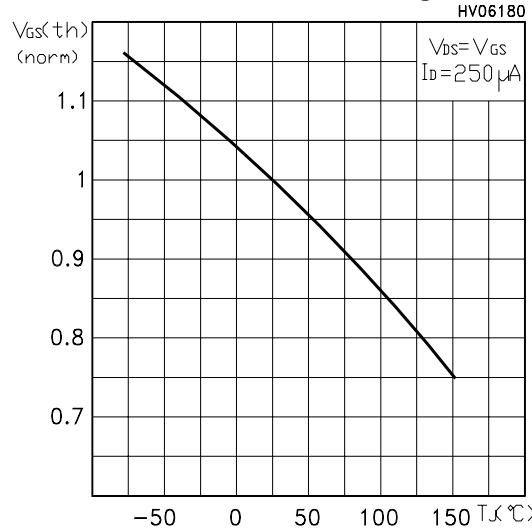
### Gate Charge vs Gate-source Voltage



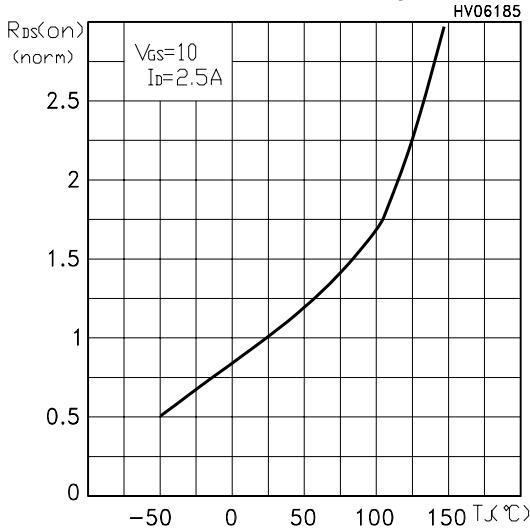
### Capacitance Variations



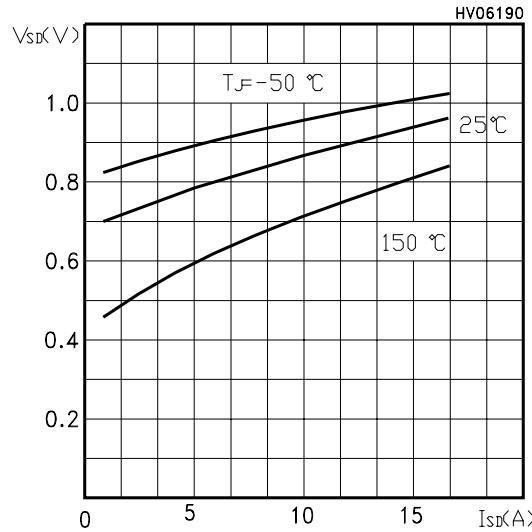
### Normalized Gate Threshold Voltage vs Temp.



### Normalized On Resistance vs Temperature

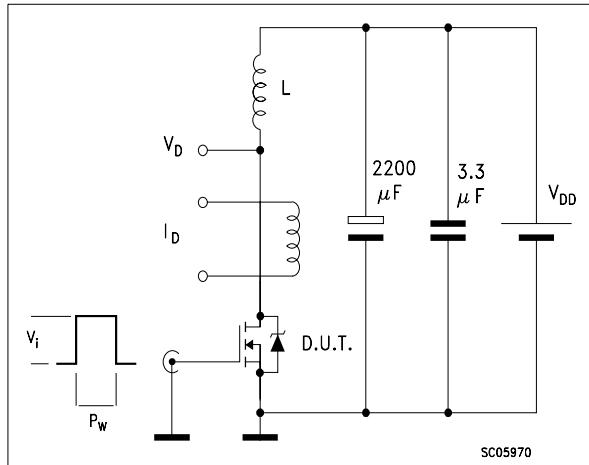


### Source-drain Diode Forward Characteristics

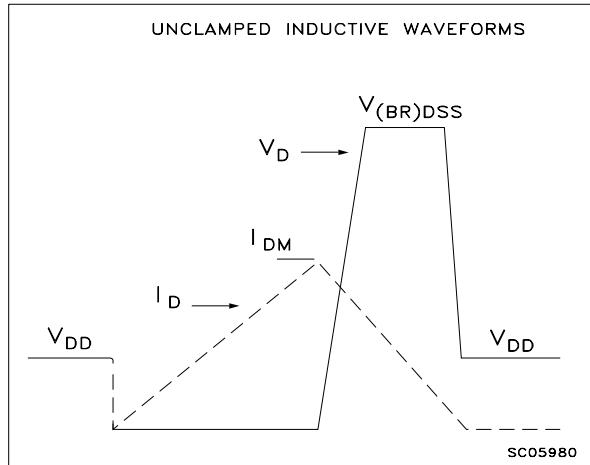


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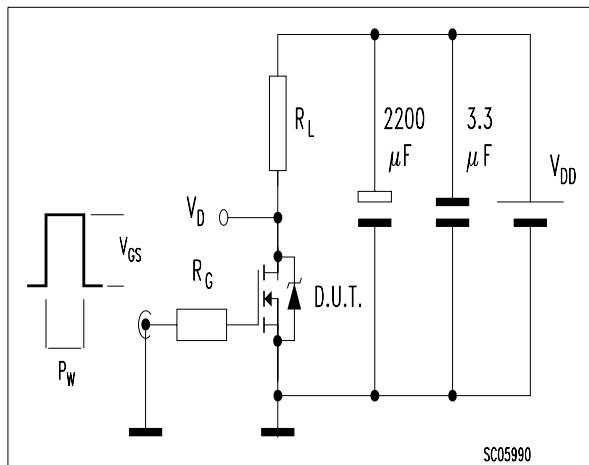
**Fig. 1:** Unclamped Inductive Load Test Circuit



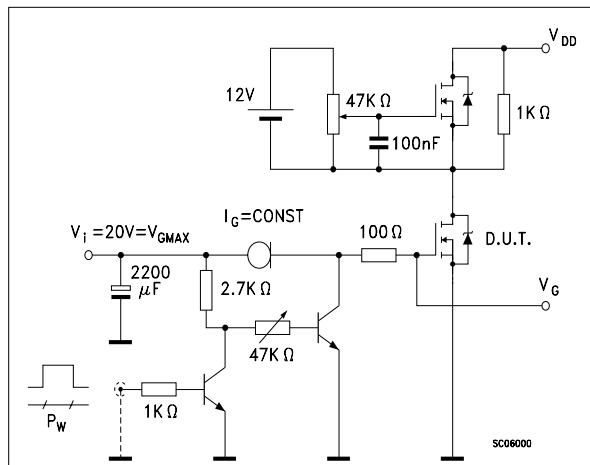
**Fig. 2:** Unclamped Inductive Waveform



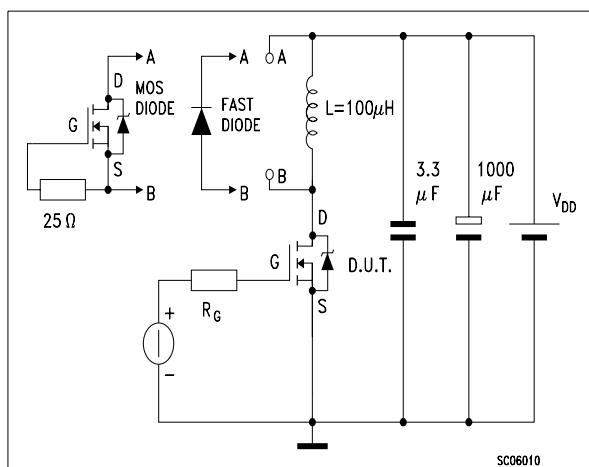
**Fig. 3:** Switching Times Test Circuit For Resistive Load



**Fig. 4:** Gate Charge test Circuit

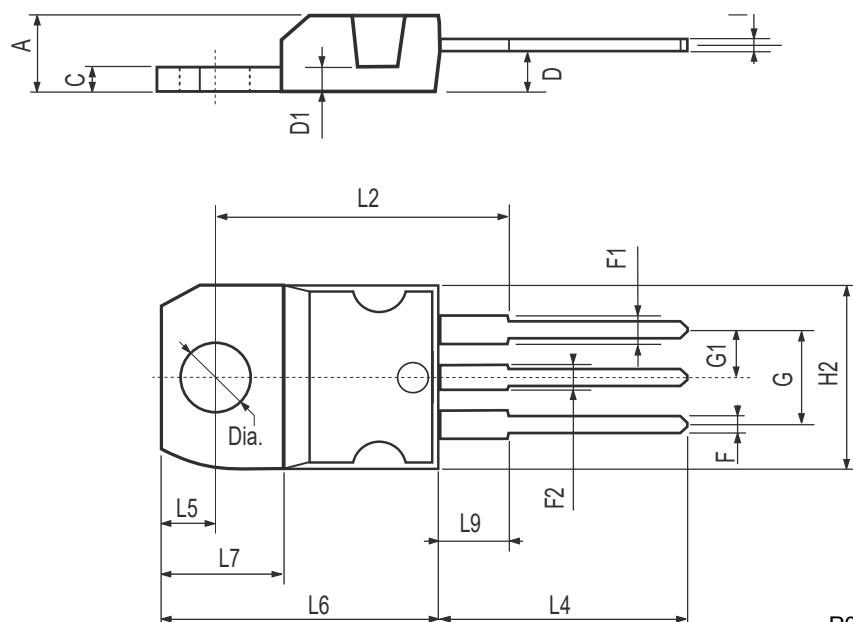


**Fig. 5:** Test Circuit For Inductive Load Switching And Diode Recovery Times



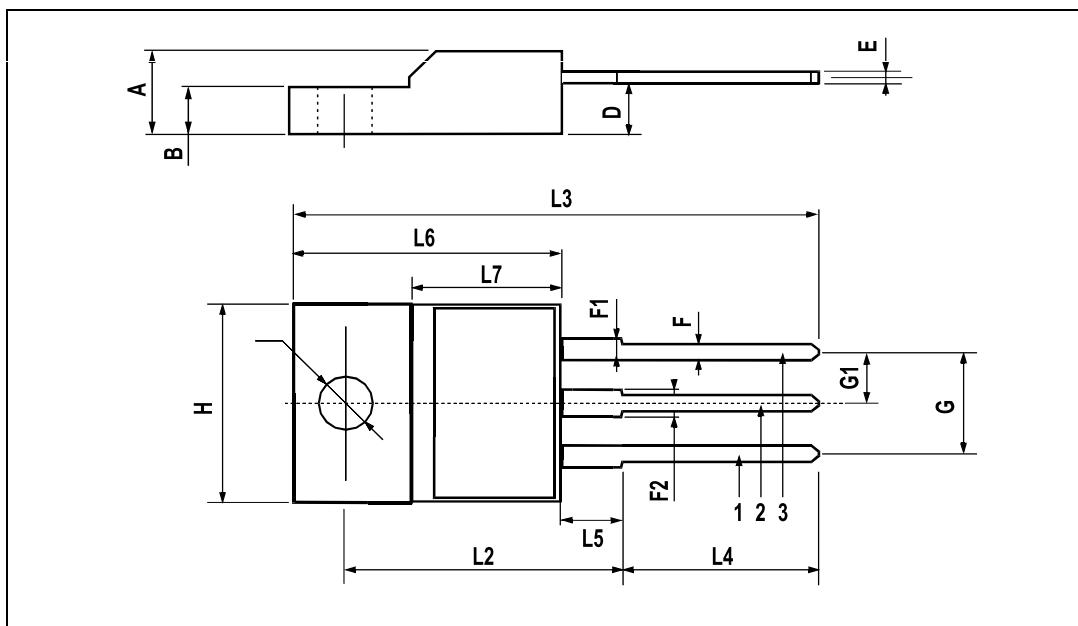
## TO-220 MECHANICAL DATA

DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	4.40		4.60	0.173		0.181
C	1.23		1.32	0.048		0.051
D	2.40		2.72	0.094		0.107
D1		1.27			0.050	
E	0.49		0.70	0.019		0.027
F	0.61		0.88	0.024		0.034
F1	1.14		1.70	0.044		0.067
F2	1.14		1.70	0.044		0.067
G	4.95		5.15	0.194		0.203
G1	2.4		2.7	0.094		0.106
H2	10.0		10.40	0.393		0.409
L2		16.4			0.645	
L4	13.0		14.0	0.511		0.551
L5	2.65		2.95	0.104		0.116
L6	15.25		15.75	0.600		0.620
L7	6.2		6.6	0.244		0.260
L9	3.5		3.93	0.137		0.154
DIA.	3.75		3.85	0.147		0.151



## TO-220FP MECHANICAL DATA

DIM.	mm.			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	4.4		4.6	0.173		0.181
B	2.5		2.7	0.098		0.106
D	2.5		2.75	0.098		0.108
E	0.45		0.7	0.017		0.027
F	0.75		1	0.030		0.039
F1	1.15		1.7	0.045		0.067
F2	1.15		1.7	0.045		0.067
G	4.95		5.2	0.195		0.204
G1	2.4		2.7	0.094		0.106
H	10		10.4	0.393		0.409
L2		16			0.630	
L3	28.6		30.6	1.126		1.204
L4	9.8		10.6	.0385		0.417
L5	2.9		3.6	0.114		0.141
L6	15.9		16.4	0.626		0.645
L7	9		9.3	0.354		0.366
Ø	3		3.2	0.118		0.126



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